

LNA IC for VHF and UHF Band (40 MHz to 900 MHz) Applications

FEATURES

- Low voltage operation +1.8 V to +2.5 V typ.
- Low current consumption
 - 5.5 mA typ. (High-Gain mode / $V_{CC} = 1.8\text{ V}$)
 - 1 μA typ. (Low-Gain mode / $V_{CC} = 1.8\text{ V}$)
- High gain
 - 14.5 dB typ. $f_{RX} = 470\text{ MHz}$ (High-Gain mode / $V_{CC} = 1.8\text{ V}$)
- Low noise figure
 - 1.36 dB typ. $f_{RX} = 470\text{ MHz}$ (High-Gain mode / $V_{CC} = 1.8\text{ V}$)
- Low distortion (IIP3 +10 MHz offset)
 - 1.5 dBm typ. $f_{RX} = 470\text{ MHz}$ (High-Gain mode / $V_{CC} = 1.8\text{ V}$)
- Small package 5 pin Plastic Small Surface Mount Package (SMINI Type)

DESCRIPTION

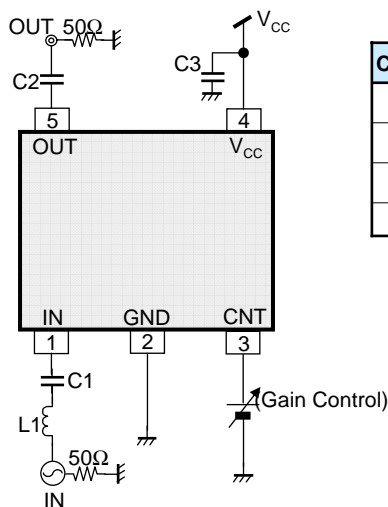
AN26072A is LNA-IC for VHF and UHF Band (40 MHz to 900 MHz) Applications. Realizing high performance by using SiGe Bi-CMOS process ($f_T = 90\text{ GHz}$, $f_{max} = 140\text{ GHz}$). High/Low Gain-mode is changeable, controlled by integrated CMOS logic circuit. Achieving miniaturization by using small size package.

APPLICATIONS

- DTV(VHF/UHF)

SIMPLIFIED APPLICATION

TOP VIEW



Components	Size	Value	Part Number	Vendor
C1	0603	1 000 pF	GRM033B11C102KD01	Murata
C2	0603	1 000 pF	GRM033B11C102KD01	Murata
C3	0603	0.1 uF	GRM033B30J104KE18	Murata
L1	0603	6.8 nH	LQP03T6N8H04	Murata

Notes) This application circuit is an example. The operation of mass production set is not guaranteed. You should perform enough evaluation and verification on the design of mass production set. You are fully responsible for the incorporation of the above application circuit and information in the design of your equipment.

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Rating	Unit	Note
Supply voltage	V_{CC}	3.6	V	*1
Supply current	I_{CC}	18	mA	—
Operating ambient temperature	T_{opr}	-20 to 70	°C	*2
Operating junction temperature	T_j	-40 to +125	°C	*2
Storage temperature	T_{stg}	-55 to +125	°C	*2
Input Voltage Range	IN (Pin No.1)	—	V	*3
	CNT (Pin No.3)	-0.3 to ($V_{CC} + 0.3$)	V	*4
	OUT (Pin No.5)	—	V	*5
ESD	HBM (Human Body Model)	2	kV	—
	MM (Machine Model)	100	V	—

Notes). This product may sustain permanent damage if subjected to conditions higher than the above stated absolute maximum rating. This rating is the maximum rating and device operating at this range is not guaranteeable as it is higher than our stated recommended operating range.

When subjected under the absolute maximum rating for a long time, the reliability of the product may be affected.

*1: The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

*2: Except for the power dissipation, operating ambient temperature, and storage temperature, all ratings are for $T_a = 25^\circ\text{C}$.

*3: RF signal input pin. Do not apply DC current.

*4: ($V_{CC} + 0.3$) V must not be exceeded 3.6 V

*5: RF signal output pin. Do not apply DC current.

POWER DISSIPATION RATING

PACKAGE	θ_{JA}	PD ($T_a=25^\circ\text{C}$)	PD ($T_a=70^\circ\text{C}$)
SSMINI-5DC	833.3°C/W	0.12W	0.06W

Note). For the actual usage, please refer to the PD- T_a characteristics diagram in the package specification, supply voltage, load and ambient temperature conditions to ensure that there is enough margin follow the power and the thermal design does not exceed the allowable value.



CAUTION

Although this has limited built-in ESD protection circuit, but permanent damage may occur on it. Therefore, proper ESD precautions are recommended to avoid electrostatic damage to the MOS gates

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Min.	Typ.	Max.	Unit	Note
Supply voltage range	V_{CC}	1.70	2.50	3.00	V	*1

Note) *1 : The values under the condition not exceeding the above absolute maximum ratings and the power dissipation.

ELECTRICAL CHARACTERISTICS

V_{cc} = 2.5 V T_a = 25°C±2°C unless otherwise specified.

Parameter	Symbol	Condition	Limits			Unit	Note
			Min	Typ	Max		
DC electrical characteristics							
Supply current HG	I _{ccHA}	V _{cc} current at High-Gain mode No input signal	—	5.7	7.7	mA	
Supply current LG	I _{ccLA}	V _{cc} current at Low-Gain mode No input signal	—	1	10	μA	
Input voltage (High-Gain mode)	V _{IHA}	—	1.40	2.50	—	V	
Input voltage (Low-Gain mode)	V _{IILA}	—	—	0.0	0.55	V	
SW current (High)	I _{IHA}	Current at CNT pin V _{IHA} = V _{cc}	—	1	10	μA	

ELECTRICAL CHARACTERISTICS (continued)

V_{cc} = 1.8 V T_a = 25°C±2°C unless otherwise specified.

Parameter	Symbol	Condition	Limits			Unit	Note
			Min	Typ	Max		
DC electrical characteristics							
Supply current HG	I _{ccHB}	V _{cc} current at High-Gain mode No input signal	—	5.5	7.5	mA	—
Supply current LG	I _{ccLB}	V _{cc} current at Low-Gain mode No input signal	—	1	10	μA	—
Input voltage (High-Gain mode)	V _{IHB}	—	1.40	2.50	—	V	—
Input voltage (Low-Gain mode)	V _{ILB}	—	—	0.0	0.55	V	—

ELECTRICAL CHARACTERISTICS (continued)

Vcc = 2.5 V Ta = 25°C±2°C, fRX = 470 MHz, PRX = -30 dBm, CW unless otherwise specified

Parameter	Symbol	Condition	Limits			Unit	Note
			Min	Typ	Max		
LNA AC electrical characteristics							
Power Gain HG	GHSA	High-Gain mode f = fRX	13	15	17	dB	—
Power Gain LG	GLSA	Low-Gain mode f = fRX, PRX = -20 dBm	-1.8	-1.3	—	dB	—
IIP3 +10 MHz offset	IIP31SA	f1 = fRX + 10 MHz f2 = fRX + 20 MHz Input 2 signals (f1, f2)	-7.5	-1.0	—	dBm	—

ELECTRICAL CHARACTERISTICS (continued)

V_{CC} = 1.8 V T_a = 25°C±2°C, f_{RX} = 470 MHz, P_{RX} = -30 dBm, CW unless otherwise specified

Parameter	Symbol	Condition	Limits			Unit	Note
			Min	Typ	Max		
LNA AC electrical characteristics							
Power Gain HG	GHSB	High-Gain mode f = f _{RX}	12.5	14.5	16.5	dB	—
Power Gain LG	GLSB	Low-Gain mode f = f _{RX} , P _{RX} = -20 dBm	-2.0	-1.5	—	dB	—
IIP3 +10 MHz offset	IIP31SB	f1 = f _{RX} + 10 MHz f2 = f _{RX} + 20 MHz Input 2 signals (f1, f2)	-8.0	-1.5	—	dBm	—

APPLICATION INFORMATION
REFERENCE VALUES FOR DESIGN

Notes) $V_{cc} = 2.5\text{ V}$

$T_a = 25^\circ\text{C} \pm 2^\circ\text{C}$, $f_{RXa} = 40\text{ MHz}, 470\text{ MHz}, 900\text{ MHz}$, $PRX = -30\text{ dBm}$, CW unless otherwise specified.

Parameter	Symbol	Condition	Reference values			Unit	Note
			Min	Typ	Max		
LNA AC electrical characteristics							
Power Gain HG	GHAa	High-Gain mode $f = f_{RXa}$	12.5	15	17.5	dB	*1
Power Gain LG	GLAa	Low-Gain mode $f = f_{RXa}$, $PRX = -20\text{ dBm}$	-3.3	-1.3	—	dB	*1
Noise Figure HG	NFHAa	High-Gain mode $f = f_{RXa}$	—	1.4	2.1	dB	*1,*2
Noise Figure LG	NFLAa	Low-Gain mode $f = f_{RXa}$	—	1.8	3.8	dB	*1
IIP3 +10 MHz offset HG	IIP3H1Aa	High-Gain mode $f_1 = f_{RXa} + 10\text{ MHz}$ $f_2 = f_{RXa} + 20\text{ MHz}$ Input 2 signals (f_1, f_2)	-10.5	-1	—	dBm	*1
Input P1dB	IP1dBHAa	High-Gain mode $f = f_{RXa}$	-17.5	-11.5	—	dBm	*1
Reverse Isolation HG	ISOHAa	High-Gain mode $f = f_{RXa}$	—	-24	-18	dB	*1
Reverse Isolation LG	ISOAa	Low-Gain mode $f = f_{RXa}$	—	-1.3	-0.4	dB	*1
Input Return Loss HG	S11HAa	High-Gain mode $f = f_{RXa}$	5	16	—	dB	*1
Input Return Loss LG	S11LAa	Low-Gain mode $f = f_{RXa}$	7	23.5	—	dB	*1
Output Return Loss HG	S22HAa	High-Gain mode $f = f_{RXa}$	5	11	—	dB	*1
Output Return Loss LG	S22LAa	Low-Gain mode $f = f_{RXa}$	8	16	—	dB	*1

Note) *1 : Checked by design, not production tested.

*2 : Connector & pattern (evaluation PCB) loss (0.01 dB at $f_{RX} = 40\text{ MHz}$, 0.04 dB at $f_{RX} = 470\text{ MHz}$, 0.08 dB at $f_{RX} = 900\text{ MHz}$) included.

APPLICATION INFORMATION (continued)

REFERENCE VALUES FOR DESIGN (continued)

Notes) $V_{cc} = 1.8\text{ V}$

$T_a = 25^\circ\text{C} \pm 2^\circ\text{C}$, $f_{RXa} = 40\text{ MHz}, 470\text{ MHz}, 900\text{ MHz}$, $PRX = -30\text{ dBm}$, CW unless otherwise specified.

Parameter	Symbol	Condition	Reference values			Unit	Note
			Min	Typ	Max		
LNA AC electrical characteristics							
Power Gain HG	GHBa	High-Gain mode $f = f_{RXa}$	12	14.5	17	dB	*1
Power Gain LG	GLBa	Low-Gain mode $f = f_{RXa}$, $PRX = -20\text{ dBm}$	-3.5	-1.5	—	dB	*1
Noise Figure HG	NFHBa	High-Gain mode $f = f_{RXa}$	—	1.4	2.1	dB	*1,*2
Noise Figure LG	NFLBa	Low-Gain mode $f = f_{RXa}$	—	2	4	dB	*1
IIP3 +10 MHz offset HG	IIP3H1Ba	High-Gain mode $f_1 = f_{RXa} + 10\text{ MHz}$ $f_2 = f_{RXa} + 20\text{ MHz}$ Input 2 signals (f_1, f_2)	-11	-1.5	—	dBm	*1
Input P1dB	IP1dBHBa	High-Gain mode $f = f_{RXa}$	-18	-12	—	dBm	*1
Reverse Isolation HG	ISOHBa	High-Gain mode $f = f_{RXa}$	—	-24	-18	dB	*1
Reverse Isolation LG	ISOLBa	Low-Gain mode $f = f_{RXa}$	—	-1.5	-0.6	dB	*1
Input Return Loss HG	S11HBa	High-Gain mode $f = f_{RXa}$	5	14	—	dB	*1
Input Return Loss LG	S11LBa	Low-Gain mode $f = f_{RXa}$	7	26	—	dB	*1
Output Return Loss HG	S22HBa	High-Gain mode $f = f_{RXa}$	7	13	—	dB	*1
Output Return Loss LG	S22LBa	Low-Gain mode $f = f_{RXa}$	8	15	—	dB	*1

Note) *1 : Checked by design, not production tested.

*2 : Connector & pattern (evaluation PCB) loss (0.01 dB at $f_{RX} = 40\text{ MHz}$, 0.04 dB at $f_{RX} = 470\text{ MHz}$, 0.08 dB at $f_{RX} = 900\text{ MHz}$) included.

APPLICATION INFORMATION (continued)

REFERENCE VALUES FOR DESIGN (continued)

Notes) $V_{cc} = 2.5\text{ V}$

$T_a = 25^\circ\text{C} \pm 2^\circ\text{C}$, $f_{RXb} = 470\text{ MHz}, 620\text{ MHz}, 770\text{ MHz}$, $PRX = -30\text{ dBm}$, CW unless otherwise specified.

Parameter	Symbol	Condition	Reference values			Unit	Note
			Min	Typ	Max		
LNA AC electrical characteristics							
Power Gain HG	GHA _b	High-Gain mode $f = f_{RXb}$	12.8	14.8	17.2	dB	*1
Power Gain LG	GLA _b	Low-Gain mode $f = f_{RXb}$, $PRX = -20\text{ dBm}$	-2.7	-1.5	—	dB	*1
Noise Figure HG	NFHA _b	High-Gain mode $f = f_{RXb}$	—	1.4	1.9	dB	*1,*3
Noise Figure LG	NFLA _b	Low-Gain mode $f = f_{RXb}$	—	2.0	3.2	dB	*1
IIP3 +10 MHz offset HG	IIP3H1A _b	High-Gain mode $f_1 = f_{RXb} + 10\text{ MHz}$ $f_2 = f_{RXb} + 20\text{ MHz}$ Input 2 signals (f_1, f_2)	-8.0	0	—	dBm	*1
Input P1dB	IP1dBHA _b	High-Gain mode $f = f_{RXb}$	-16	-12	—	dBm	*1
Reverse Isolation HG	ISOHA _b	High-Gain mode $f = f_{RXb}$	—	-24	-18	dB	*1
Reverse Isolation LG	ISOA _b	Low-Gain mode $f = f_{RXb}$	—	-1.5	-0.9	dB	*1
Input Return Loss HG	S11HA _b	High-Gain mode $f = f_{RXb}$	8	17	—	dB	*1
Input Return Loss LG	S11LA _b	Low-Gain mode $f = f_{RXb}$	9	16	—	dB	*1
Output Return Loss HG	S22HA _b	High-Gain mode $f = f_{RXb}$	7	12	—	dB	*1
Output Return Loss LG	S22LA _b	Low-Gain mode $f = f_{RXb}$	9	13	—	dB	*1

Note) *1 : Checked by design, not production tested.

*3 : Connector & pattern (evaluation PCB) loss (0.04 dB at $f_{RX} = 470\text{ MHz}$, 0.05 dB at $f_{RX} = 620\text{ MHz}$, 0.06 dB at $f_{RX} = 770\text{ MHz}$) included.

APPLICATION INFORMATION (continued)

REFERENCE VALUES FOR DESIGN (continued)

Notes) $V_{cc} = 1.8\text{ V}$

$T_a = 25^\circ\text{C} \pm 2^\circ\text{C}$, $f_{RXb} = 470\text{ MHz}, 620\text{ MHz}, 770\text{ MHz}$, $PRX = -30\text{ dBm}$, CW unless otherwise specified.

Parameter	Symbol	Condition	Reference values			Unit	Note
			Min	Typ	Max		
LNA AC electrical characteristics							
Power Gain HG	GHBb	High-Gain mode $f = f_{RXb}$	12.3	14.3	16.7	dB	*1
Power Gain LG	GLBb	Low-Gain mode $f = f_{RXb}$, $PRX = -20\text{ dBm}$	-2.9	-1.7	—	dB	*1
Noise Figure HG	NFHBb	High-Gain mode $f = f_{RXb}$	—	1.4	1.9	dB	*1,*3
Noise Figure LG	NFLBb	Low-Gain mode $f = f_{RXb}$	—	2.2	3.4	dB	*1
IIP3 +10 MHz offset HG	IIP3H1Bb	High-Gain mode $f_1 = f_{RXb} + 10\text{ MHz}$ $f_2 = f_{RXb} + 20\text{ MHz}$ Input 2 signals (f_1, f_2)	-8.5	-0.5	—	dBm	*1
Input P1dB	IP1dBHBb	High-Gain mode $f = f_{RXb}$	-17	-13	—	dBm	*1
Reverse Isolation HG	ISOHBb	High-Gain mode $f = f_{RXb}$	—	-24	-18	dB	*1
Reverse Isolation LG	ISOLBb	Low-Gain mode $f = f_{RXb}$	—	-1.7	-1.1	dB	*1
Input Return Loss HG	S11HBb	High-Gain mode $f = f_{RXb}$	8	16	—	dB	*1
Input Return Loss LG	S11LBb	Low-Gain mode $f = f_{RXb}$	9.5	17	—	dB	*1
Output Return Loss HG	S22HBb	High-Gain mode $f = f_{RXb}$	7	13	—	dB	*1
Output Return Loss LG	S22LBb	Low-Gain mode $f = f_{RXb}$	8	12	—	dB	*1

Note) *1 : Checked by design, not production tested.

*3 : Connector & pattern (evaluation PCB) loss (0.04 dB at $f_{RX} = 470\text{ MHz}$, 0.05 dB at $f_{RX} = 620\text{ MHz}$, 0.06 dB at $f_{RX} = 770\text{ MHz}$) included.

APPLICATION INFORMATION (continued)

REFERENCE VALUES FOR DESIGN (continued)

Notes) $V_{CC} = 2.5\text{ V}$

$T_a = 25^\circ\text{C} \pm 2^\circ\text{C}$, $f_{RXc} = 207.5\text{ MHz}$, 215 MHz , 222 MHz , $PRX = -30\text{ dBm}$, CW unless otherwise specified.

Parameter	Symbol	Condition	Reference values			Unit	Note
			Min	Typ	Max		
LNA AC electrical characteristics							
Power Gain HG	GHAc	High-Gain mode $f = f_{RXc}$	12.7	14.5	17.3	dB	*1
Power Gain LG	GLAc	Low-Gain mode $f = f_{RXc}$, $PRX = -20\text{ dBm}$	-1.5	-1.0	—	dB	*1
Noise Figure HG	NFHAc	High-Gain mode $f = f_{RXc}$	—	1.2	1.7	dB	*1,*4
Noise Figure LG	NFLAc	Low-Gain mode $f = f_{RXc}$	—	1.5	3.3	dB	*1
IIP3 +10 MHz offset HG	IIP3H1Ac	High-Gain mode $f_1 = f_{RXc} + 10\text{ MHz}$ $f_2 = f_{RXc} + 20\text{ MHz}$ Input 2 signals (f_1, f_2)	-9.5	-2	—	dBm	*1
Input P1dB	IP1dBHAc	High-Gain mode $f = f_{RXc}$	-14	-10	—	dBm	*1
Reverse Isolation HG	ISOHAc	High-Gain mode $f = f_{RXc}$	—	-25	-19	dB	*1
Reverse Isolation LG	ISOAc	Low-Gain mode $f = f_{RXc}$	—	-1.0	-0.4	dB	*1
Input Return Loss HG	S11HAc	High-Gain mode $f = f_{RXc}$	7	7.5	—	dB	*1
Input Return Loss LG	S11LAc	Low-Gain mode $f = f_{RXc}$	20	25	—	dB	*1
Output Return Loss HG	S22HAc	High-Gain mode $f = f_{RXc}$	7	11	—	dB	*1
Output Return Loss LG	S22LAc	Low-Gain mode $f = f_{RXc}$	15	20	—	dB	*1

Note) *1 : Checked by design, not production tested.

*4 : Connector & pattern (evaluation PCB) loss 0.03dB included.

APPLICATION INFORMATION (continued)

REFERENCE VALUES FOR DESIGN (continued)

Notes) $V_{cc} = 1.8\text{ V}$

$T_a = 25^\circ\text{C} \pm 2^\circ\text{C}$, $f_{RXc} = 207.5\text{ MHz}$, 215 MHz , 222 MHz , $PRX = -30\text{ dBm}$, CW unless otherwise specified.

Parameter	Symbol	Condition	Reference values			Unit	Note
			Min	Typ	Max		
LNA AC electrical characteristics							
Power Gain HG	GHBc	High-Gain mode $f = f_{RXc}$	12.9	14.7	16.8	dB	*1
Power Gain LG	GLBc	Low-Gain mode $f = f_{RXc}$, $PRX = -20\text{ dBm}$	-1.7	-1.2	—	dB	*1
Noise Figure HG	NFHBc	High-Gain mode $f = f_{RXc}$	—	1.2	1.6	dB	*1,*4
Noise Figure LG	NFLBc	Low-Gain mode $f = f_{RXc}$	—	1.7	3.5	dB	*1
IIP3 +10 MHz offset HG	IIP3H1Bc	High-Gain mode $f_1 = f_{RXc} + 10\text{ MHz}$ $f_2 = f_{RXc} + 20\text{ MHz}$ Input 2 signals (f_1, f_2)	-10	-2.5	—	dBm	*1
Input P1dB	IP1dBHBc	High-Gain mode $f = f_{RXc}$	-16.5	-12.5	—	dBm	*1
Reverse Isolation HG	ISOHBc	High-Gain mode $f = f_{RXc}$	—	-25	-19	dB	*1
Reverse Isolation LG	ISOLBc	Low-Gain mode $f = f_{RXc}$	—	-1.2	-0.6	dB	*1
Input Return Loss HG	S11HBc	High-Gain mode $f = f_{RXc}$	7	8	—	dB	*1
Input Return Loss LG	S11LBc	Low-Gain mode $f = f_{RXc}$	17	22	—	dB	*1
Output Return Loss HG	S22HBc	High-Gain mode $f = f_{RXc}$	7	15	—	dB	*1
Output Return Loss LG	S22LBc	Low-Gain mode $f = f_{RXc}$	13	18	—	dB	*1

Note) *1 : Checked by design, not production tested.

*4 : Connector & pattern (evaluation PCB) loss 0.03dB included.

APPLICATION INFORMATION (continued)

REFERENCE VALUES FOR DESIGN (continued)

Notes) $V_{cc} = 2.5\text{ V}$

$T_a = 25^\circ\text{C} \pm 2^\circ\text{C}$, $f_{RXd} = 90\text{ MHz}, 99\text{ MHz}, 108\text{ MHz}$, $PRX = -30\text{ dBm}$, CW unless otherwise specified.

Parameter	Symbol	Condition	Reference values			Unit	Note
			Min	Typ	Max		
LNA AC electrical characteristics							
Power Gain HG	GHA _d	High-Gain mode $f = f_{RXd}$	12.7	14.5	17.2	dB	*1
Power Gain LG	GLA _d	Low-Gain mode $f = f_{RXd}$, $PRX = -20\text{ dBm}$	-1.4	-0.9	—	dB	*1
Noise Figure HG	NFHA _d	High-Gain mode $f = f_{RXd}$	—	1.2	1.7	dB	*1,*5
Noise Figure LG	NFLA _d	Low-Gain mode $f = f_{RXd}$	—	1.4	3.1	dB	*1
IIP3 +10 MHz offset HG	IIP3H1A _d	High-Gain mode $f_1 = f_{RXd} + 10\text{ MHz}$ $f_2 = f_{RXd} + 20\text{ MHz}$ Input 2 signals (f_1, f_2)	-10.5	-1	—	dBm	*1
Input P1dB	IP1dBHA _d	High-Gain mode $f = f_{RXd}$	-13.5	-9.5	—	dBm	*1
Reverse Isolation HG	ISOHA _d	High-Gain mode $f = f_{RXd}$	—	-25	-19	dB	*1
Reverse Isolation LG	ISOA _d	Low-Gain mode $f = f_{RXd}$	—	-0.9	-0.4	dB	*1
Input Return Loss HG	S11HA _d	High-Gain mode $f = f_{RXd}$	6	6.5	—	dB	*1
Input Return Loss LG	S11LA _d	Low-Gain mode $f = f_{RXd}$	16	21	—	dB	*1
Output Return Loss HG	S22HA _d	High-Gain mode $f = f_{RXd}$	7	11	—	dB	*1
Output Return Loss LG	S22LA _d	Low-Gain mode $f = f_{RXd}$	15	20	—	dB	*1

Note) *1 : Checked by design, not production tested.

*5 : Connector & pattern (evaluation PCB) loss 0.02dB included.

APPLICATION INFORMATION (continued)

REFERENCE VALUES FOR DESIGN (continued)

Notes) $V_{cc} = 1.8\text{ V}$

$T_a = 25^\circ\text{C} \pm 2^\circ\text{C}$, $f_{RXd} = 90\text{ MHz}, 99\text{ MHz}, 108\text{ MHz}$, $PRX = -30\text{ dBm}$, CW unless otherwise specified.

Parameter	Symbol	Condition	Reference values			Unit	Note
			Min	Typ	Max		
LNA AC electrical characteristics							
Power Gain HG	GHBd	High-Gain mode $f = f_{RXd}$	12.9	14.7	16.9	dB	*1
Power Gain LG	GLBd	Low-Gain mode $f = f_{RXd}$, $PRX = -20\text{ dBm}$	-1.6	-1.1	—	dB	*1
Noise Figure HG	NFHBd	High-Gain mode $f = f_{RXd}$	—	1.2	1.7	dB	*1,*5
Noise Figure LG	NFLBd	Low-Gain mode $f = f_{RXd}$	—	1.6	3.3	dB	*1
IIP3 +10 MHz offset HG	IIP3H1Bd	High-Gain mode $f_1 = f_{RXd} + 10\text{ MHz}$ $f_2 = f_{RXd} + 20\text{ MHz}$ Input 2 signals (f_1, f_2)	-11	-1	—	dBm	*1
Input P1dB	IP1dBHBd	High-Gain mode $f = f_{RXd}$	-16.5	-12.5	—	dBm	*1
Reverse Isolation HG	ISOHBd	High-Gain mode $f = f_{RXd}$	—	-25	-19	dB	*1
Reverse Isolation LG	ISOLBd	Low-Gain mode $f = f_{RXd}$	—	-1.1	-0.6	dB	*1
Input Return Loss HG	S11HBd	High-Gain mode $f = f_{RXd}$	6	7	—	dB	*1
Input Return Loss LG	S11LBd	Low-Gain mode $f = f_{RXd}$	15	20	—	dB	*1
Output Return Loss HG	S22HBd	High-Gain mode $f = f_{RXd}$	7	16	—	dB	*1
Output Return Loss LG	S22LBd	Low-Gain mode $f = f_{RXd}$	14	19	—	dB	*1

Note) *1 : Checked by design, not production tested.

*5 : Connector & pattern (evaluation PCB) loss 0.02dB included.

APPLICATION INFORMATION (continued)

REFERENCE VALUES FOR DESIGN (continued)

Notes) $V_{cc} = 1.7\text{ V to }3.0\text{ V}$
 $T_a = -20^{\circ}\text{C to }70^{\circ}\text{C}$

Parameter	Symbol	Condition	Reference values			Unit	Note
			Min	Typ	Max		
DC electrical characteristics							
Supply current HG	I _{ccHT}	V _{cc} current at High-Gain mode No input signal	—	5.7	8.2	mA	*1
Supply current LG	I _{ccLT}	V _{cc} current at Low-Gain mode No input signal	—	1	11	μA	*1
Input voltage (High-Gain mode)	V _{IHT}	—	1.50	2.50	—	V	*1
Input voltage (Low-Gain mode)	V _{ILT}	—	—	0.0	0.40	V	*1
SW current (High)	I _{IHT}	Current at CNT pin V _{IHT} = V _{cc}	—	1	11	μA	*1

Note) *1 : Checked by design, not production tested.

APPLICATION INFORMATION (continued)

REFERENCE VALUES FOR DESIGN (continued)

Notes) $V_{cc} = 1.7\text{ V to }3.0\text{ V}$

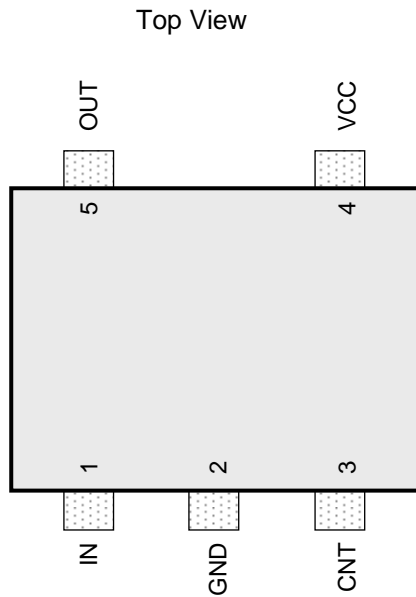
$T_a = -20^\circ\text{C to }70^\circ\text{C}$, $f_{RXa} = 40\text{ MHz, }470\text{ MHz, }900\text{ MHz}$, $PRX = -30\text{ dBm, CW}$

Parameter	Symbol	Condition	Reference values			Unit	Note
			Min	Typ	Max		
LNA AC electrical characteristics							
Power Gain HG	GHT	High-Gain mode $f = f_{RXa}$	11.5	15	18.5	dB	*1
Power Gain LG	GLT	Low-Gain mode $f = f_{RXa}$, $PRX = -20\text{ dBm}$	-3.8	-1.3	—	dB	*1
Noise Figure HG	NFHT	High-Gain mode $f = f_{RXa}$	—	1.4	2.5	dB	*1,*2
Noise Figure LG	NFLT	Low-Gain mode $f = f_{RXa}$	—	1.8	4.3	dB	*1
IIP3 +10 MHz offset HG	IIP3H1T	High-Gain mode $f_1 = f_{RXa} + 10\text{ MHz}$ $f_2 = f_{RXa} + 20\text{ MHz}$ Input 2 signals (f_1, f_2)	-13.0	-1.0	—	dBm	*1
Input P1dB HG	IP1dBHT	High-Gain mode $f = f_{RXa}$	-20	-11.5	—	dBm	*1

Note) *1 : Checked by design, not production tested.

*2 : Connector & pattern (evaluation PCB) loss (0.01 dB at $f_{RX} = 40\text{ MHz}$, 0.04 dB at $f_{RX} = 470\text{ MHz}$, 0.08 dB at $f_{RX} = 900\text{ MHz}$) included.

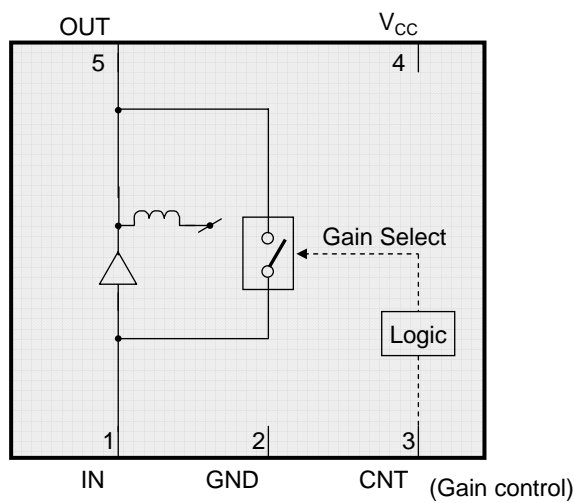
PIN CONFIGURATION



PIN FUNCTIONS

Pin No.	Pin name	Type	Description
1	IN	Input	RF Input
2	GND	Ground	GND
3	CNT	Input	High-Gain / Low-Gain switch L: Low-Gain Mode H: High-Gain Mode
4	VCC	Power Supply	V _{CC}
5	OUT	Output	RF Output

FUNCTIONAL BLOCK DIAGRAM

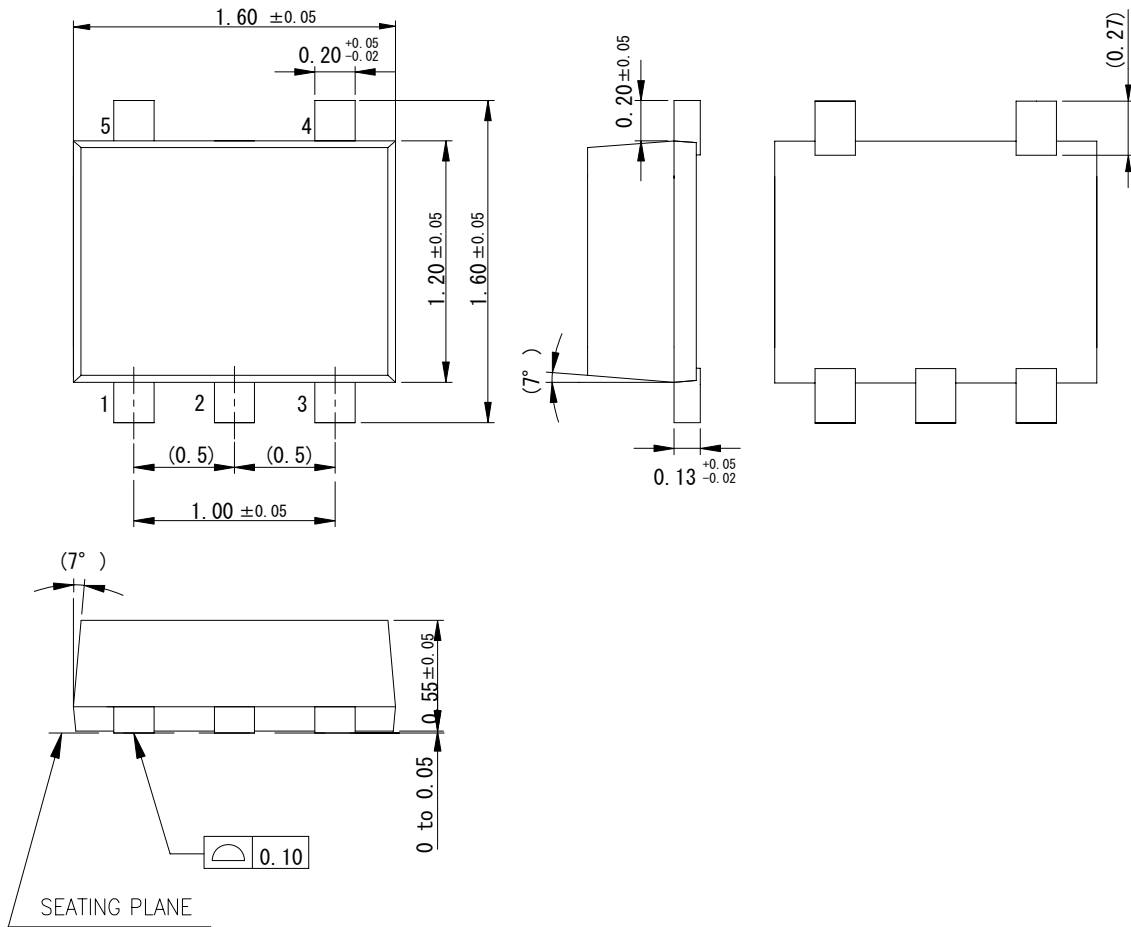


Notes) This circuit and these circuit constants show an example and do not guarantee the design as a mass-production set. This block diagram is for explaining functions. The part of the block diagram may be omitted, or it may be simplified.

PACKAGE INFORMATION (Reference Data)

Package Code:SSMINI-5DC

Unit:mm



Body Material	: Br / Sb Free Epoxy Resin
Lead Material	: Cu Alloy
Lead Finish Method	: SnBi Plating

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5. Perform a visual inspection on the PCB before applying power, otherwise damage might happen due to problems such as a solder-bridge between the pins of the semiconductor device. Also, perform a full technical verification on the assembly quality, because the same damage possibly can happen due to conductive substances, such as solder ball, that adhere to the LSI during transportation.
6. Take notice in the use of this product that it might break or occasionally smoke when an abnormal state occurs such as output pin-VCC short (Power supply fault), output pin-GND short (Ground fault), or output-to-output-pin short (load short) .

And, safety measures such as an installation of fuses are recommended because the extent of the above-mentioned damage and smoke emission will depend on the current capability of the power supply.

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